

Features

- Advanced Shield Gate Trench technology
- Super Low Gate Charge
- High-Speed Switching
- 100% EAS Guaranteed
- Green Device Available

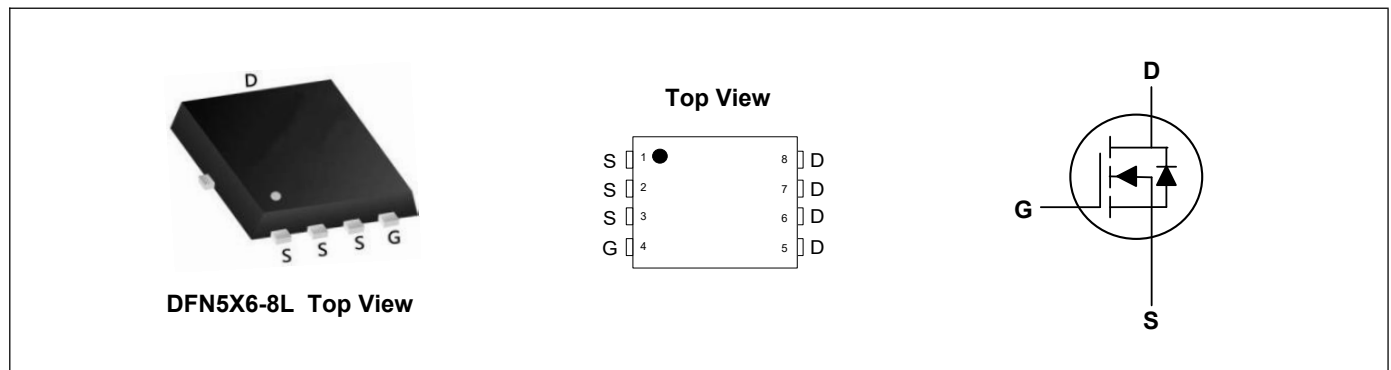
Applications

- High Frequency Point-of-Load, Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch

Product Summary



| | | |
|----------------------------------|-----|------------|
| V_{DS} | 100 | V |
| I_D | 120 | A |
| $R_{DS(ON)}$ (at $V_{GS}=10V$) | 4.5 | m Ω |
| $R_{DS(ON)}$ (at $V_{GS}=4.5V$) | 6.8 | m Ω |



Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | Rating | Units |
|--|-----------|------------|------------------|
| Drain-Source Voltage | V_{DS} | 100 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current ¹ | I_D | 120 | A |
| Continuous Drain Current ¹ | I_D | 63 | A |
| Pulsed Drain Current ² | I_{DM} | 480 | A |
| Single Pulse Avalanche Energy ³ | E_{AS} | 320 | mJ |
| Total Power Dissipation ⁴ | P_D | 131.6 | W |
| Storage Temperature Range | T_{STG} | -55 to 150 | $^\circ\text{C}$ |
| Operating Junction Temperature Range | T_J | -55 to 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Unit |
|--|-----------------|-----|------|--------------------|
| Thermal Resistance Junction-Ambient ¹ | $R_{\theta JA}$ | --- | 48 | $^\circ\text{C/W}$ |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | --- | 0.95 | $^\circ\text{C/W}$ |

Electrical Characteristics (T_J=25°C, unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------------------------------|---------------------|---|-----|------|------|------|
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V, I _D =250uA | 100 | --- | --- | V |
| Static Drain-Source On-Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =20A | --- | 3.6 | 4.5 | mΩ |
| | | V _{GS} =4.5V, I _D =15A | --- | 5.2 | 6.8 | mΩ |
| Gate Threshold Voltage | V _{GS(th)} | V _{GS} =V _{DS} , I _D =250uA | 1.2 | 1.8 | 2.5 | V |
| Drain-Source Leakage Current | I _{DSS} | V _{DS} =100V, V _{GS} =0V | --- | --- | 1 | uA |
| Gate-Source Leakage Current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |
| Forward Transconductance | g _{fs} | V _{DS} =5V, I _D =20A | --- | --- | --- | S |
| Total Gate Charge | Q _g | V _{DS} =50V, V _{GS} =10V, I _D =20A | --- | 103 | --- | nC |
| Gate-Source Charge | Q _{gs} | | --- | 17.5 | --- | |
| Gate-Drain Charge | Q _{gd} | | --- | 30.2 | --- | |
| Turn-On Delay Time | T _{d(on)} | V _{DS} =50V, V _{GS} =10V, R _G =3Ω, I _D =20A | --- | 22.2 | --- | ns |
| Rise Time | T _r | | --- | 37.8 | --- | |
| Turn-Off Delay Time | T _{d(off)} | | --- | 95.2 | --- | |
| Fall Time | T _f | | --- | 35.6 | --- | |
| Input Capacitance | C _{iss} | V _{DS} =50V, V _{GS} =0V, f=1MHz | --- | 5135 | --- | pF |
| Output Capacitance | C _{oss} | | --- | 768 | --- | |
| Reverse Transfer Capacitance | C _{rss} | | --- | 22 | --- | |

Drain-Source Diode Characteristics

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|------------------------------------|-----------------|--|-----|-----|-----|------|
| Diode Forward Voltage ² | V _{SD} | V _{GS} =0V, I _F =20A, T _J =25°C | --- | --- | 1.2 | V |
| Reverse Recovery Time | t _{rr} | I _F =20A | --- | 59 | --- | nS |
| Reverse Recovery Charge | Q _{rr} | di/dt=100A/μs, T _J =25°C | --- | 92 | --- | nC |

Note:

- 1.The data tested by surface mounted on a 1 inch²FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=100V,R_G=25Ω,L=0.1mH

Typical Characteristics

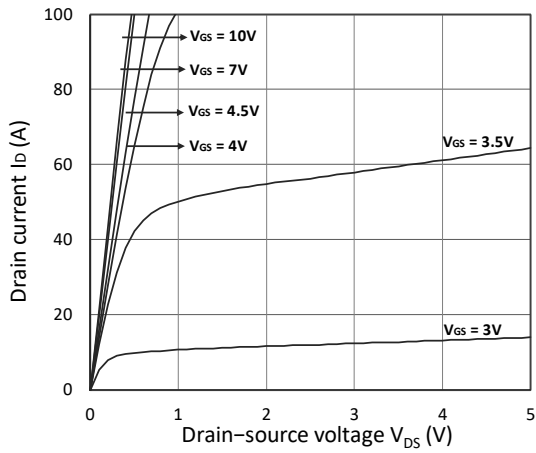


Figure 1. Output Characteristics

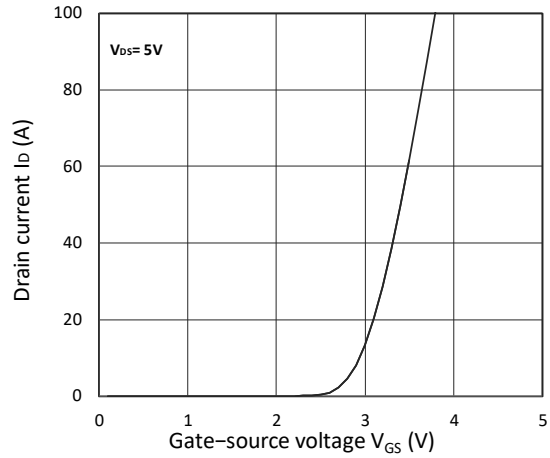


Figure 2. Transfer Characteristics

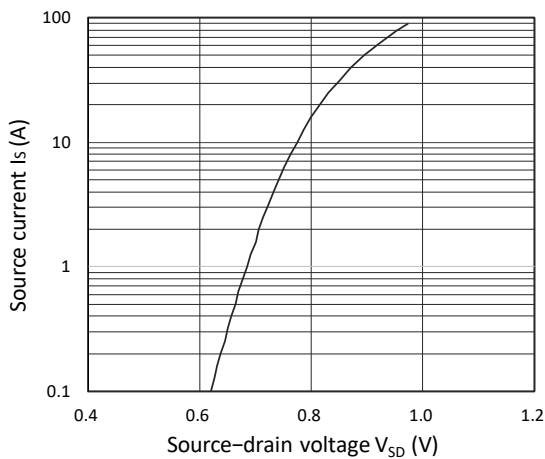


Figure 3. Forward Characteristics of Reverse

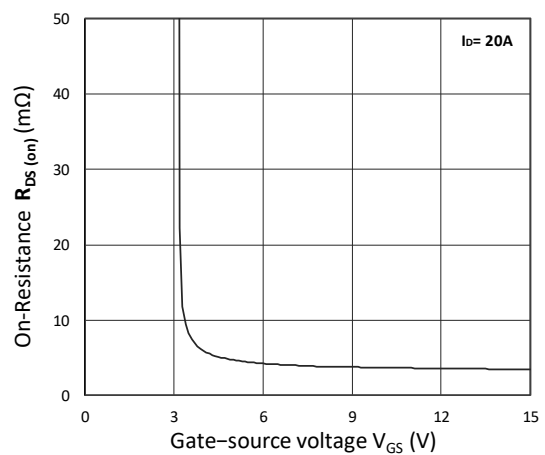


Figure 4. $R_{DS(on)}$ vs. V_{GS}

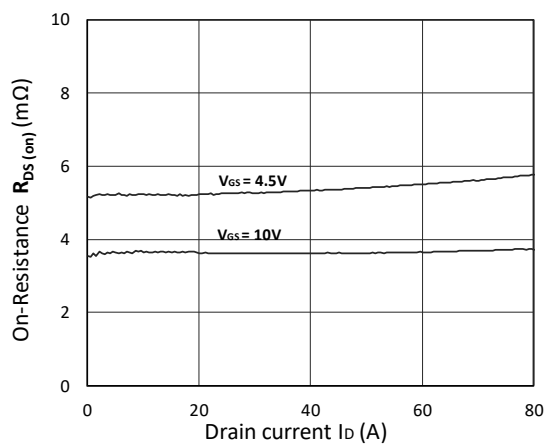


Figure 5. $R_{DS(on)}$ vs. I_D

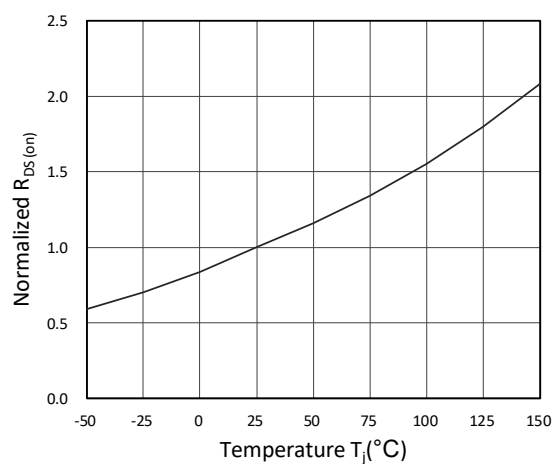


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

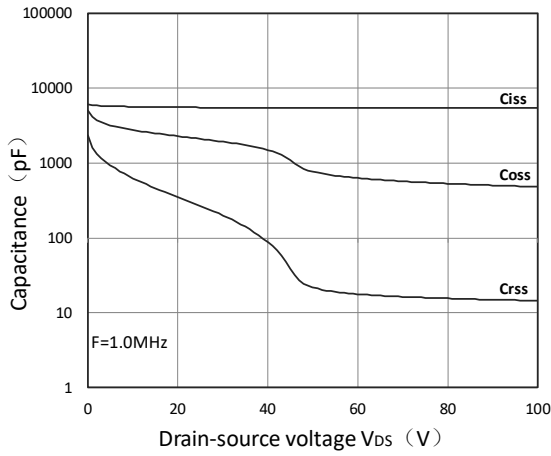


Figure 7. Capacitance Characteristics

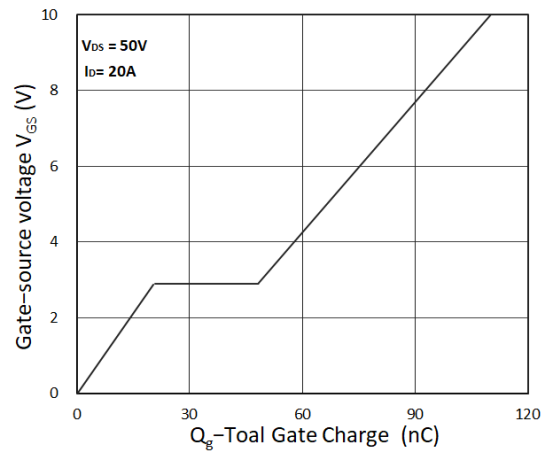


Figure 8. Gate Charge Characteristics

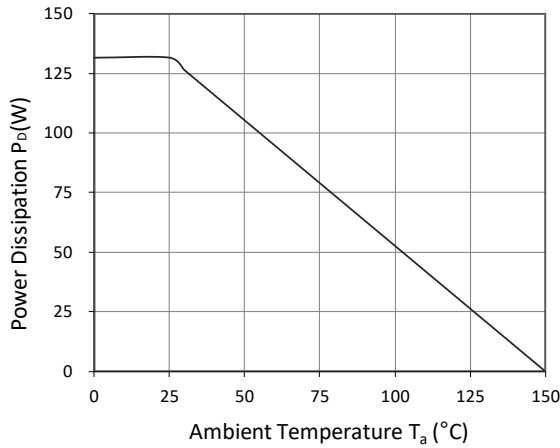


Figure 9. Power Dissipation

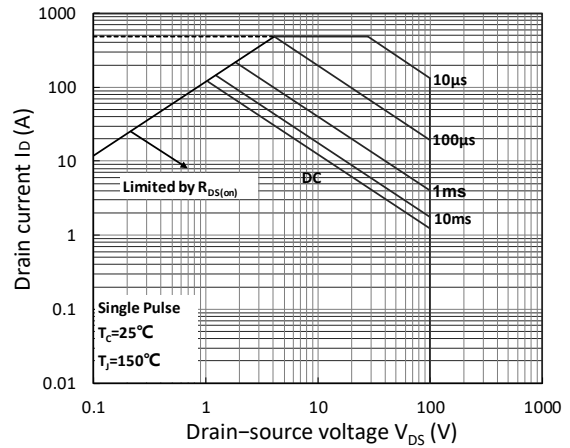


Figure 10. Safe Operating Area

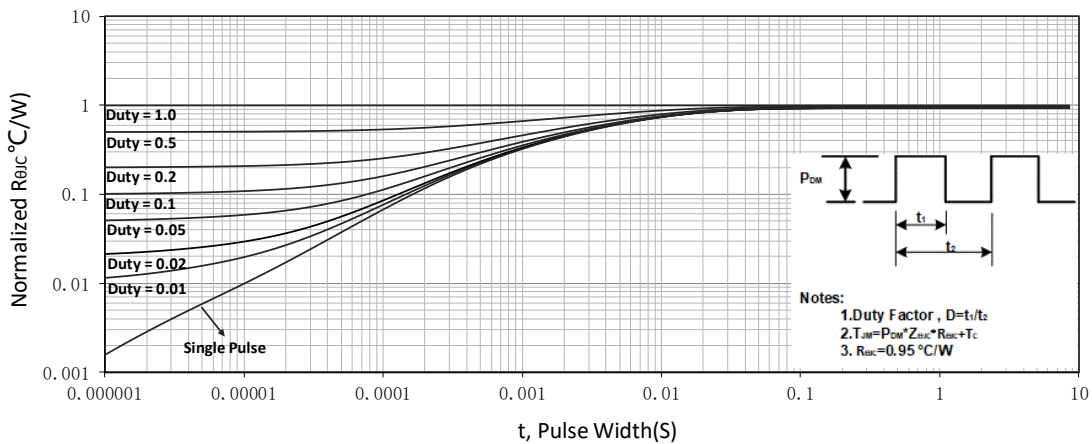
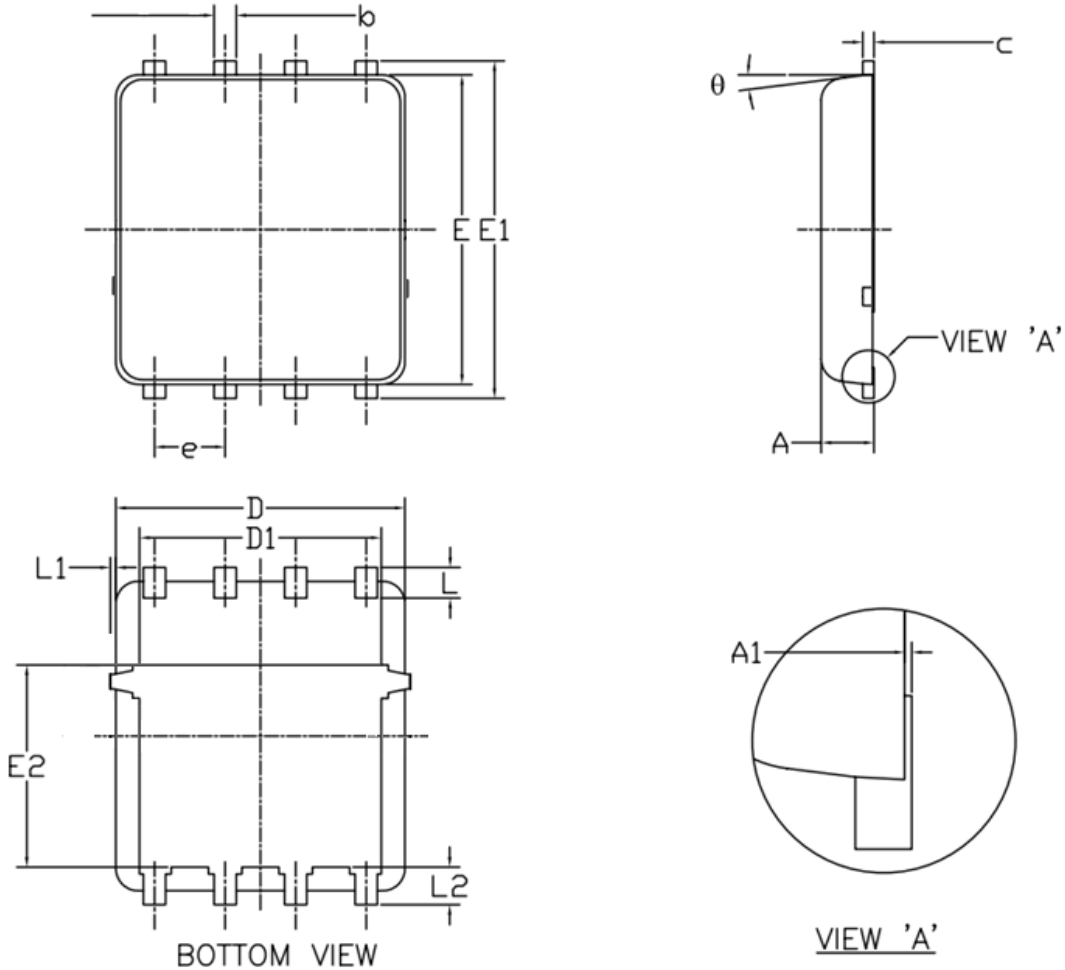


Figure 11. Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Outline Dimensions



| Symbol | Dimensions (unit:mm) | | | Symbol | Dimensions (unit:mm) | | |
|-----------|----------------------|------|------|--------------|----------------------|------|------|
| | Min | Typ | Max | | Min | Typ | Max |
| A | 0.90 | 1.00 | 1.20 | E1 | 5.90 | 6.10 | 6.35 |
| A1 | 0.00 | -- | 0.05 | E2 | 3.38 | 3.58 | 3.92 |
| b | 0.30 | 0.40 | 0.51 | e | 1.27 BSC | | |
| c | 0.20 | 0.25 | 0.33 | L | 0.51 | 0.61 | 0.71 |
| D | 4.80 | 4.90 | 5.40 | L1 | -- | -- | 0.15 |
| D1 | 3.61 | 4.00 | 4.25 | L2 | 0.41 | 0.51 | 0.61 |
| E | 5.65 | 5.80 | 6.06 | theta | 0° | -- | 12° |